Abstracts

Mixed material integration for power amplifier MMICs

B. Matinpour, J. Bergman, C. Chun, J. Laskar and N.M. Jokerst. "Mixed material integration for power amplifier MMICs." 1999 MTT-S International Microwave Symposium Digest 99.2 (1999 Vol. II [MWSYM]): 625-628 vol.2.

In this paper we present the first large signal analysis of thin film HBTs by experimental load pull measurements. InP HBTs are fully characterized before and after substrate removal and integration onto electrically insulating substrates, and show preserved small and large signal performance. In addition, we demonstrate the feasibility of integrating thin film power devices and MMICs on thermally conductive substrates for development of high efficiency power amplifiers.

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